

NTC thermistors for temperature measurement

Probe assemblies, surface mounted sensors

Series/Type: **B58100**
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Applications

- Surface mounted sensor for measurement of boiler temperature

Features

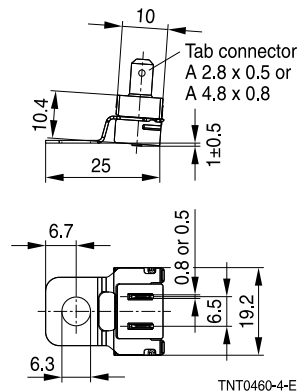
- Short response time due to glass-encapsulated NTC thermistor
- Fast and easy mounting
- Screw attachment fixation

Options

- Alternative resistance ratings available on request
- Alternative fast-on plug terminals 2.8 x 0.5 or 4.8 x 0.8 mm available

Delivery mode

Bulk

Dimensional drawing


Dimensions in mm

General technical data

Climatic category	(IEC 60068-1)		5/100/21	
Maximum power	(at 25 °C)	P_{25}	18	mW
Resistance tolerance		$\Delta R_R/R_R$	± 3.6	%
Rated temperature		T_R	60	°C
Thermal time constant	(measured on surface)	τ_a	< 5	s
Insulation resistance	(V = 100 V DC, t = 1 min)	R_{ins}	> 10	M Ω
Dissipation factor	(in air)	δ_{th}	approx. 2.1	mW/K
Test voltage	(t = 1 s)	V_{test}	500	V AC

Electrical specification and ordering codes

R_{60}	R_{25}	No. of R/T characteristic	$B_{25/100}$	$B_{0/100}$	Contact dimensions mm	Ordering code
Ω	Ω		K	K		
2500	10151	8317	4005 $\pm 1\%$	3970	2.8 x 0.5	B58100A0461A000
2500	10151	8317	4005 $\pm 1\%$	3970	4.8 x 0.8	B58100A0463A000

Reliability data

Test	Standard	Test conditions	$\Delta R_{100}/R_{100}$ (typical)	Remarks
Storage in dry heat	IEC 60068-2-2	Storage at upper category temperature T: 100 °C t: 500 h	< 3%	No visible damage
Storage in damp heat, steady state	IEC 60068-2-78	Temperature of air: 85 °C Relative humidity of air: 85% Duration: 21 days	< 5%	No visible damage
Rapid temperature cycling	IEC 60068-2-14	Lower test temperature: 5 °C Upper test temperature: 85 °C Number of cycles: 1000	< 3%	No visible damage
Thermal overload		Short time overload: 125 °C t: 10 h	< 3%	No visible damage

Note

- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals).
- Avoid dewing and condensation unless thermistor is specified for these conditions.

R/T characteristics

R/T No. 8317								
T (°C)	B _{25/100} = 4005 K		T (°C)	B _{25/100} = 4005 K		T (°C)	B _{25/100} = 4005 K	
	R _T /R ₂₅	α (%/K)		R _T /R ₂₅	α (%/K)		R _T /R ₂₅	α (%/K)
-55.0	99.49	7.4	0.0	3.304	5.2	55.0	0.29585	3.7
-50.0	69.168	7.2	5.0	2.5632	5.0	60.0	0.24629	3.6
-45.0	48.679	6.9	10.0	2.0038	4.9	65.0	0.20608	3.5
-40.0	34.662	6.7	15.0	1.5783	4.7	70.0	0.17327	3.4
-35.0	24.959	6.5	20.0	1.252	4.6	75.0	0.14638	3.3
-30.0	18.166	6.3	25.0	1.0000	4.4	80.0	0.12422	3.2
-25.0	13.358	6.1	30.0	0.80403	4.3	85.0	0.10588	3.2
-20.0	9.9201	5.9	35.0	0.6506	4.2	90.0	0.090628	3.1
-15.0	7.4369	5.7	40.0	0.52967	4.1	95.0	0.07789	3.0
-10.0	5.6261	5.5	45.0	0.43377	3.9	100.0	0.067207	2.9
-5.0	4.2935	5.3	50.0	0.35726	3.8	—	—	—

Cautions and warnings

General

See "Important notes" on page 2.

Storage

- Store thermistors only in original packaging. Do not open the package prior to processing.
- Storage conditions in original packaging: storage temperature $-25\text{ }^{\circ}\text{C} \dots +45\text{ }^{\circ}\text{C}$, relative humidity $\leq 75\%$ annual mean, $< 95\%$ maximum 30 days per annum, dew precipitation is inadmissible.
- Do not store thermistors where they are exposed to heat or direct sunlight. Otherwise, the packing material may be deformed or components may stick together, causing problems during mounting.
- Avoid contamination of thermistor surface during storage, handling and processing.
- Avoid storage of thermistors in harmful environments like corrosive gases (SO_x , Cl etc).
- Use the components as soon as possible after opening the original packaging.
- Solder thermistors within the time specified after shipment from EPCOS.
For leaded components this is 24 months, for SMD components with nickel barrier termination 12 months, for leadless components this is 12 months, for SMD components with AgPd termination 6 months.

Handling

- NTC thermistors must not be dropped. Chip-offs or any other damage must not be caused during handling of NTCs.
- Do not touch components with bare hands. Gloves are recommended.
- Avoid contamination of thermistor surface during handling.
- Washing processes may damage the product due to the possible static or cyclic mechanical loads (e.g. ultrasonic cleaning). They may cause cracks to develop on the product and its parts, which might lead to reduced reliability or lifetime.

Bending / twisting leads

- A lead (wire) may be bent at a minimum distance of twice the wire's diameter plus 4 mm from the component head or housing. When bending ensure the wire is mechanically relieved at the component head or housing. The bending radius should be at least 0.75 mm.

Soldering

- Use resin-type flux or non-activated flux.
- Insufficient preheating may cause ceramic cracks.
- Rapid cooling by dipping in solvent is not recommended.
- Complete removal of flux is recommended.

Mounting

- Ensure that no thermo-mechanical stress occurs due to production processes (curing or overmolding processes) when thermistors are sealed, potted or overmolded or during their subsequent operation. The maximum temperature of the thermistor must not be exceeded. Ensure that the materials used (sealing/potting compound and plastic material) are chemically neutral.
- Electrodes/contacts must not be scratched or damaged before/during/after the mounting process.
- Contacts and housing used for assembly with the thermistor must be clean before mounting.
- Ensure that adjacent materials are designed for operation at temperatures comparable to the surface temperature of the thermistor. Be sure that surrounding parts and materials can withstand the temperature.
- Avoid contamination of the thermistor surface during processing.
- The connections of sensors (e.g. cable end, wire end, plug terminal) may only be exposed to an environment with normal atmospheric conditions.
- Tensile forces on cables or leads must be avoided during mounting and operation.
- Bending or twisting of cables or leads directly on the thermistor body is not permissible.
- Avoid using chemical substances as mounting aids. It must be ensured that no water or other liquids enter the NTC thermistors (e.g. through plug terminals). In particular, water based substances (e.g. soap suds) must not be used as mounting aids for sensors.
- The use of no-clean solder products is recommended. In any case mild, non-activated fluxes should be used. Flux residues after soldering should be minimized.

Operation

- Use thermistors only within the specified operating temperature range.
- Use thermistors only within the specified power range.
- Environmental conditions must not harm the thermistors. Only use the thermistors under normal atmospheric conditions or within the specified conditions.
- Contact of NTC thermistors with any liquids and solvents shall be prevented. It must be ensured that no water enters the NTC thermistors (e.g. through plug terminals). For measurement purposes (checking the specified resistance vs. temperature), the component must not be immersed in water but in suitable liquids (e.g. perfluoropolyethers such as Galden).
- Avoid dewing and condensation unless thermistor is specified for these conditions.
- Bending or twisting of cables and/or wires is not permissible during operation of the sensor in the application.
- Be sure to provide an appropriate fail-safe function to prevent secondary product damage caused by malfunction.

This listing does not claim to be complete, but merely reflects the experience of EPCOS AG.

Display of ordering codes for EPCOS products

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Symbols and terms

Symbol	English	German
A	Area	Fläche
AWG	American Wire Gauge	Amerikanische Norm für Drahtquerschnitte
B	B value	B-Wert
B _{25/100}	B value determined by resistance measurement at 25 °C and 100 °C	B-Wert, ermittelt durch Widerstandsmessungen bei 25 °C und 100 °C
C _{th}	Heat capacitance	Wärmekapazität
I	Current	Strom
N	Number (integer)	Anzahl (ganzzahliger Wert)
P ₂₅	Maximum power at 25 °C	Maximale Leistung bei 25 °C
P _{diss}	Power dissipation	Verlustleistung
P _{el}	Electrical power	Elektrische Leistung
P _{max}	Maximum power within stated temperature range	Maximale Leistung im angegebenen Temperaturbereich
$\Delta R_B/R_B$	Resistance tolerance caused by spread of B value	Widerstandstoleranz, die durch die Streuung des B-Wertes verursacht wird
R _{ins}	Insulation resistance	Isolationswiderstand
R _P	Parallel resistance	Parallelwiderstand
R _R	Rated resistance	Nennwiderstand
$\Delta R_R/R_R$	Resistance tolerance	Widerstandstoleranz
R _S	Series resistance	Serienwiderstand
R _T	Resistance at temperature T (e.g. R ₂₅ = resistance at 25 °C)	Widerstand bei Temperatur T (z.B. R ₂₅ = Widerstand bei 25 °C)
T	Temperature	Temperatur
ΔT	Temperature tolerance	Temperaturtoleranz
t	Time	Zeit
T _A	Ambient temperature	Umgebungstemperatur
T _{max}	Upper category temperature	Obere Grenztemperatur (Kategorietemperatur)
T _{min}	Lower category temperature	Untere Grenztemperatur (Kategorietemperatur)
T _{op}	Operating temperature	Betriebstemperatur
T _R	Rated temperature	Nenntemperatur
T _{surf}	Surface temperature	Oberflächentemperatur
V	Voltage	Spannung
V _{ins}	Insulation test voltage	Isolationsprüfspannung
V _{op}	Operating voltage	Betriebsspannung
V _{test}	Test voltage	Prüfspannung

Temperature measurement	B58100
Probe assemblies	F120

Symbol	English	German
α	Temperature coefficient	Temperaturkoeffizient
Δ	Tolerance, change	Toleranz, Änderung
δ_{th}	Dissipation factor	Wärmeleitwert
τ_c	Thermal cooling time constant	Thermische Abkühlzeitkonstante
τ_a	Thermal time constant	Thermische Zeitkonstante

Abbreviations / Notes

Symbol	English	German
<u>SMD</u>	Surface-mounted devices	Oberflächenmontierbares Bauelement
*	To be replaced by a number in ordering codes, type designations etc.	Platzhalter für Zahl im Bestellnummerncode oder für die Typenbezeichnung.
+	To be replaced by a letter. All dimensions are given in mm.	Platzhalter für einen Buchstaben. Alle Maße sind in mm angegeben.
	The commas used in numerical values denote decimal points.	Verwendete Kommas in Zahlenwerten bezeichnen Dezimalpunkte.

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Important notes

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